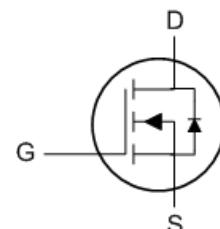


N-Ch 100V Fast Switching MOSFETs

Features:

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

SOT23 Pin Configuration



Description:

The KWN0014 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The KWN0014 meet the RoHS and Green Product requirement with full function reliability approved.

Product Summary



| BVDSS | RDS(on) | ID |
|-------|---------|-----|
| 100V | 152mΩ | 2 A |

Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|--------------------------------------|--|------------|-------|
| V _{DS} | Drain-Source Voltage | 100 | V |
| V _{GS} | Gate-Source Voltage | ±20 | V |
| I _D @T _A =25°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 2 | A |
| I _D @T _A =70°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 1.6 | A |
| I _{DM} | Pulsed Drain Current ² | 4 | A |
| P _D @T _A =25°C | Total Power Dissipation ³ | 1.5 | W |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction-ambient(steady state) ¹ | --- | 135 | °C/W |
| | Thermal Resistance Junction-ambient(t<10s) ¹ | --- | 85 | °C/W |

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|------------------------------|--|---|------|-------|-----------|----------------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$ | 100 | --- | --- | V |
| $\Delta BV_{DSS}/\Delta T_J$ | BVDSS Temperature Coefficient | Reference to 25°C , $I_D=1\text{mA}$ | --- | 0.122 | --- | $\text{V}/^\circ\text{C}$ |
| $R_{DS(\text{ON})}$ | Static Drain-Source On-Resistance ² | $V_{GS}=10\text{V}$, $I_D=2\text{A}$ | --- | --- | 152 | $\text{m}\Omega$ |
| | | $V_{GS}=4.5\text{V}$, $I_D=1\text{A}$ | --- | --- | 158 | $\text{m}\Omega$ |
| $V_{GS(\text{th})}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$ | 1.0 | 1.5 | 2.5 | V |
| $\Delta V_{GS(\text{th})}$ | $V_{GS(\text{th})}$ Temperature Coefficient | | --- | -4.84 | --- | $\text{mV}/^\circ\text{C}$ |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=80\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^\circ\text{C}$ | --- | --- | 10 | uA |
| | | $V_{DS}=80\text{V}$, $V_{GS}=0\text{V}$, $T_J=55^\circ\text{C}$ | --- | --- | 100 | |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$ | --- | --- | ± 100 | nA |
| g_{fs} | Forward Transconductance | $V_{DS}=5\text{V}$, $I_D=2\text{A}$ | --- | 10.2 | --- | S |
| R_g | Gate Resistance | $V_{DS}=0\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$ | --- | 2.3 | 4.6 | Ω |
| Q_g | Total Gate Charge (10V) | $V_{DS}=60\text{V}$, $V_{GS}=10\text{V}$, $I_D=2\text{A}$ | --- | 25.5 | --- | nC |
| Q_{gs} | Gate-Source Charge | | --- | 4.2 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 4.3 | --- | |
| $T_{d(on)}$ | Turn-On Delay Time | $V_{DD}=50\text{V}$, $V_{GS}=10\text{V}$, $R_G=3.3\Omega$ | --- | 17.3 | --- | ns |
| T_r | Rise Time | | --- | 2.8 | --- | |
| $T_{d(off)}$ | Turn-Off Delay Time | | --- | 50 | --- | |
| T_f | Fall Time | | --- | 2.8 | --- | |
| C_{iss} | Input Capacitance | $V_{DS}=15\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$ | --- | 1077 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 46 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 32 | --- | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|----------|--|---|------|------|------|------|
| I_s | Continuous Source Current ^{1,4} | $V_G=V_D=0\text{V}$, Force Current | --- | --- | 2 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{GS}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$ | --- | --- | 1.2 | V |

Note :

1. The data tested by surface mounted on a 1 inch²FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
3. The power dissipation is limited by 150°C junction temperature
4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

Typical Characteristics

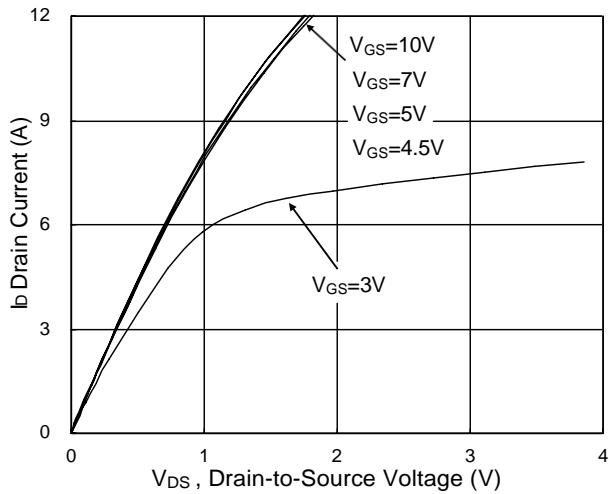


Fig.1 Typical Output Characteristics

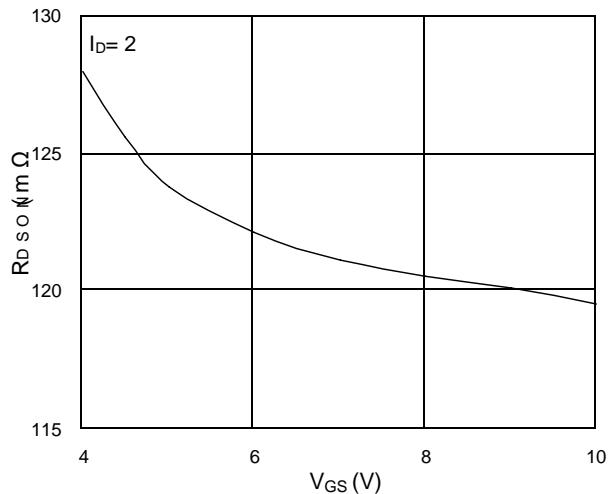


Fig.2 On-Resistance vs. Gate-Source

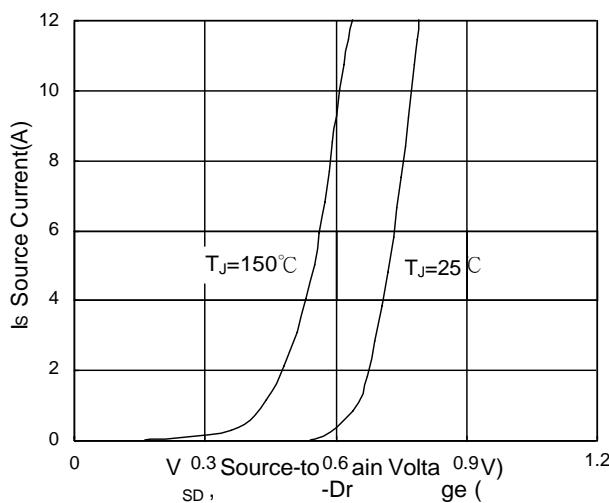


Fig.3 Forward Characteristics Of Reverse

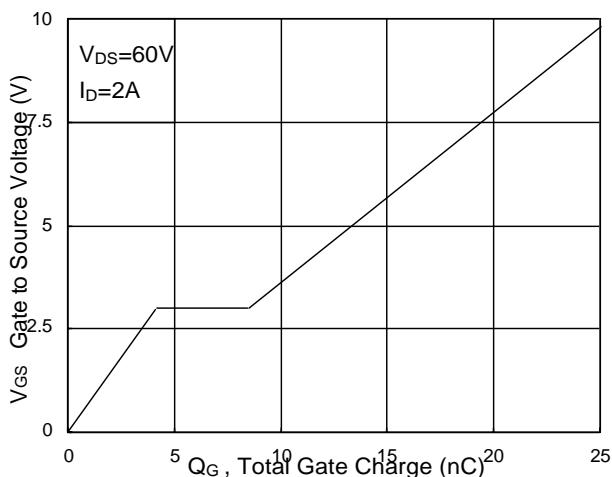


Fig.4 Gate-Charge Characteristics

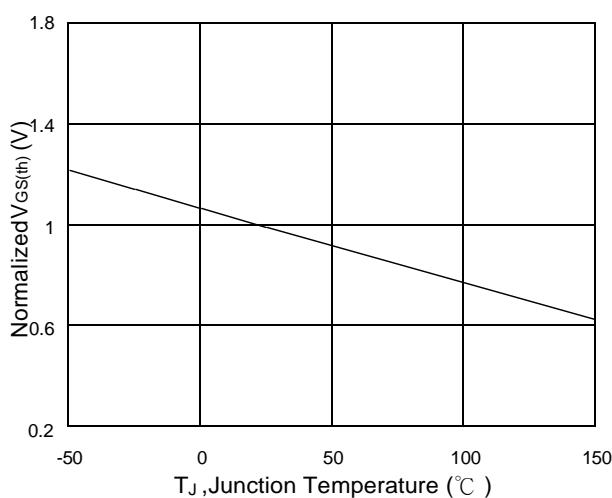


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

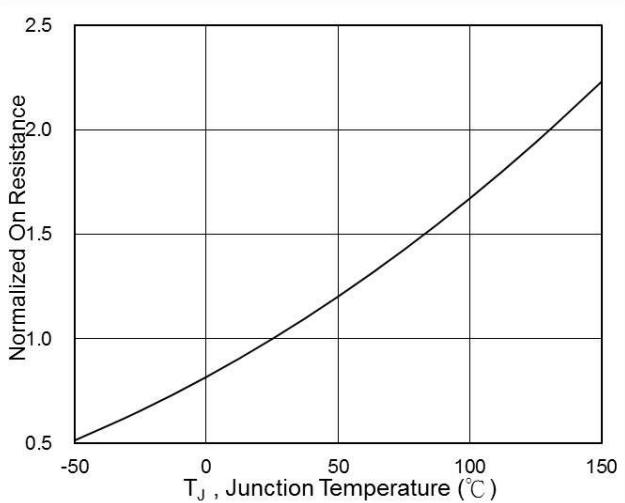


Fig.6 Normalized R_{DSON} vs. T_J

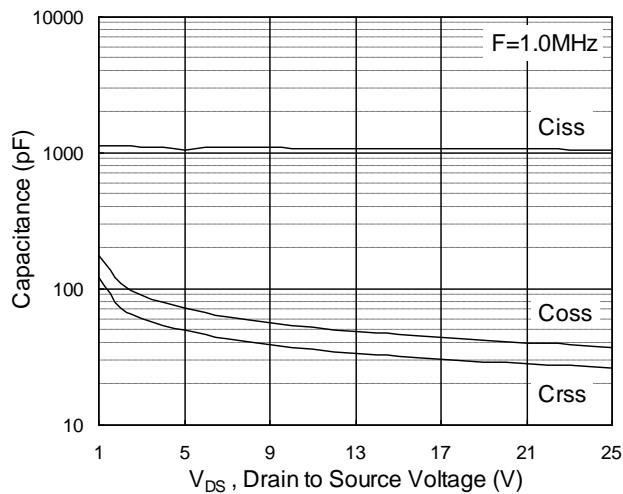


Fig.7 Capacitance

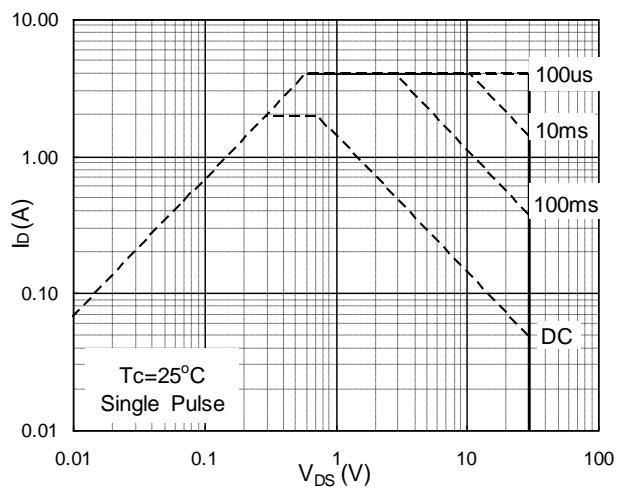


Fig.8 Safe Operating Area

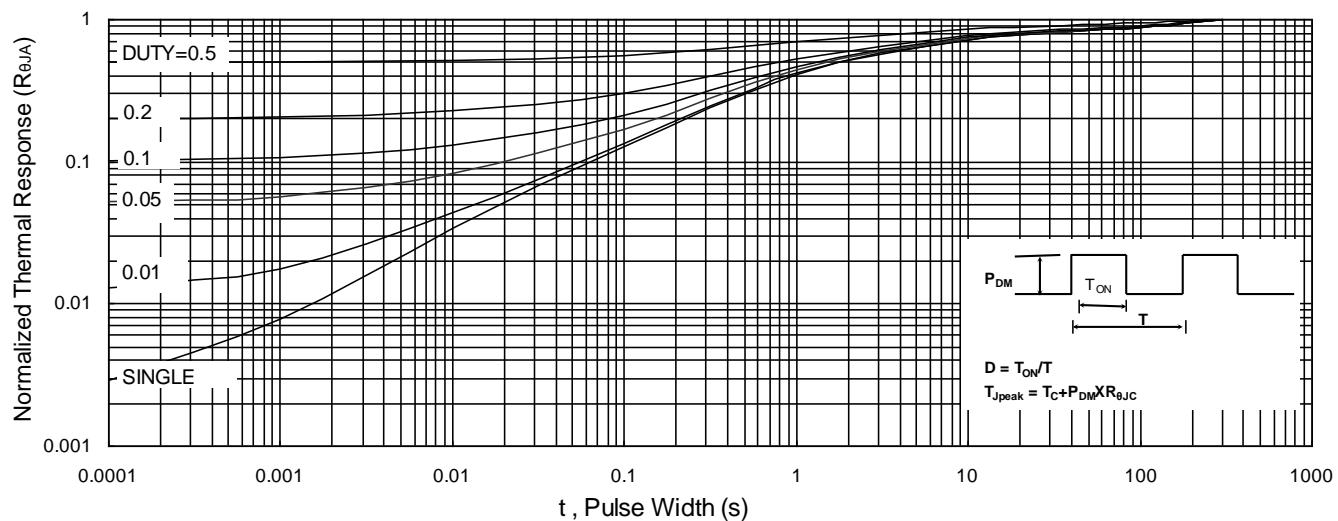


Fig.9 Normalized Maximum Transient Thermal Impedance

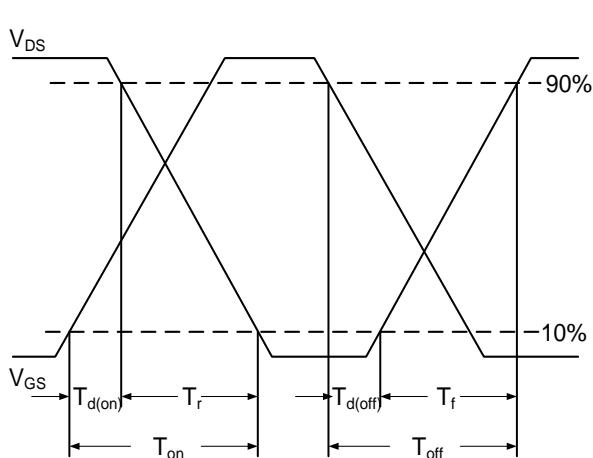


Fig.10 Switching Time Waveform

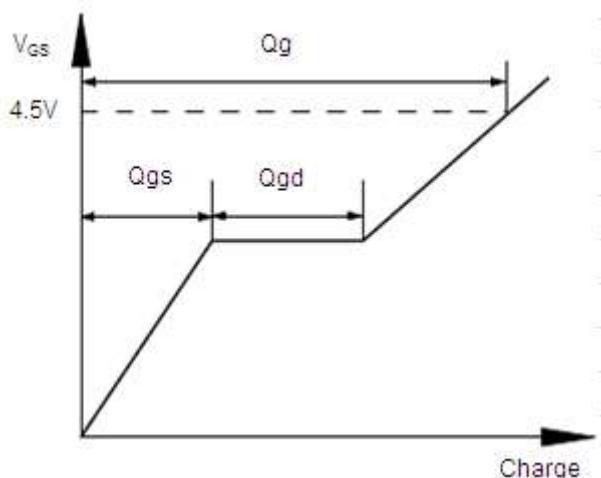
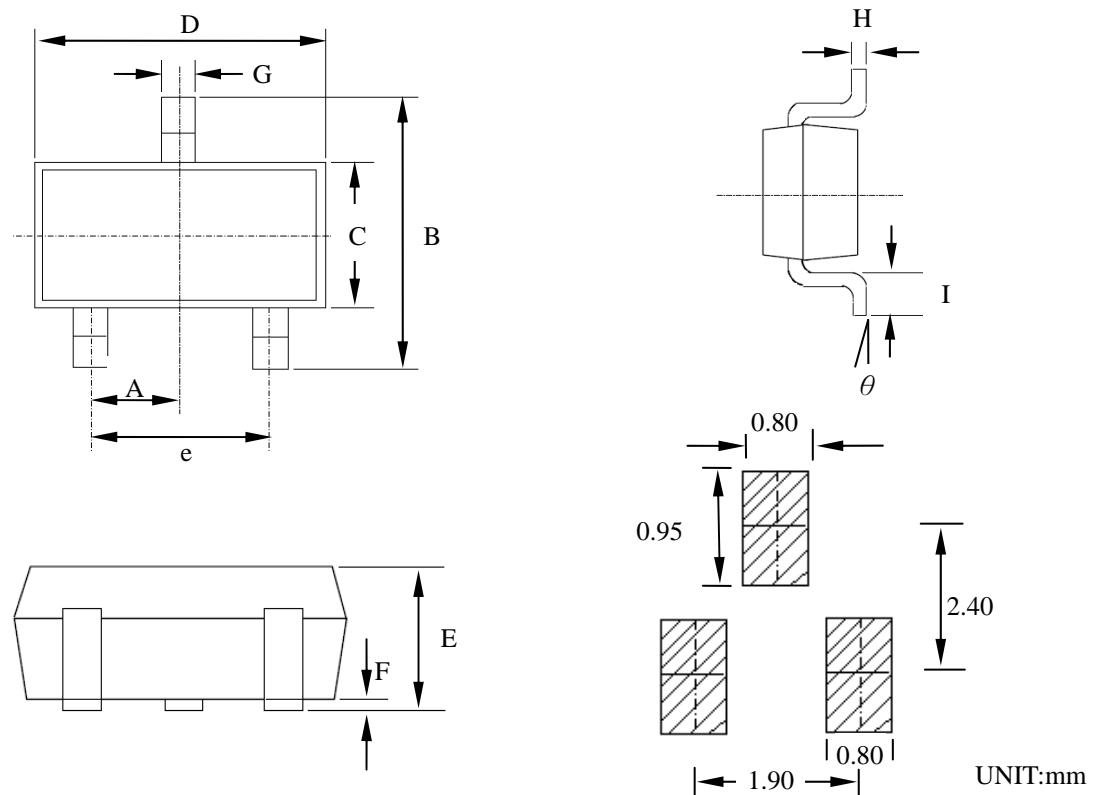


Fig.11 Gate Charge Waveform

SOT-23 Package Outline



LAND PATTERN RECOMMENDATION

| SYMBOLS | MILLIMETERS | | | INCHES | | |
|----------|-------------|-----------|-----------|-----------|-----------|-----------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.90 | 0.95 | 1.00 | 0.035 | 0.037 | 0.039 |
| B | 2.60 | 2.80 | 3.00 | 0.102 | 0.110 | 0.118 |
| C | 1.40 | 1.55 | 1.70 | 0.055 | 0.061 | 0.067 |
| D | 2.80 | 2.95 | 3.10 | 0.110 | 0.116 | 0.122 |
| E | 0.85 | -- | 1.20 | 0.033 | -- | 0.047 |
| F | 0.00 | -- | 0.10 | 0.000 | -- | 0.004 |
| G | 0.30 | 0.40 | 0.50 | 0.012 | 0.016 | 0.020 |
| H | 0.10 | -- | 0.20 | 0.004 | -- | 0.008 |
| I | 0.30 | 0.45 | 0.60 | 0.012 | 0.018 | 0.024 |
| θ | 0° | 4° | 8° | 0° | 4° | 8° |
| e | -- | 1.90 | -- | -- | 0.075 | -- |